

Rigid

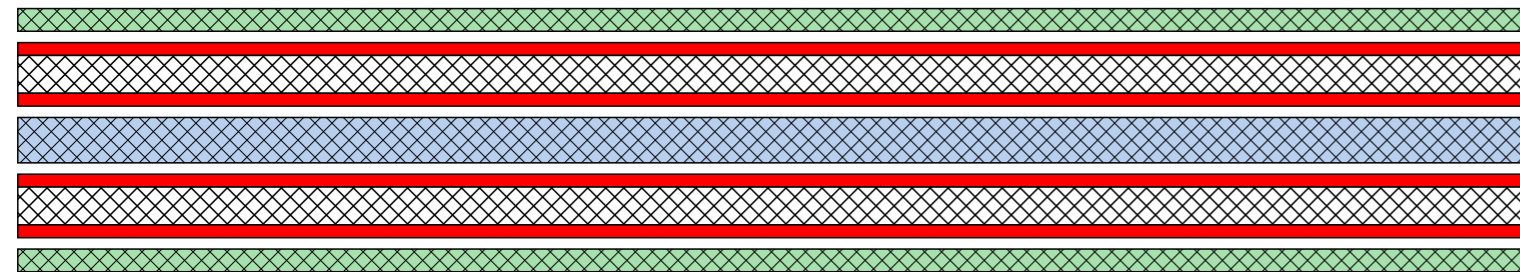
| # | Layer | Thickness | Description | Note |
|---|-----------------------|-----------|---|-----------------------------|
| | Top Solder | 0.015mm | Soldermask IPC-SM840 | used on rigid parts |
| | Top Surface Finish | 0.006mm | | |
| 1 | Top Side | 0.030mm | Starting foil 1/4oz. after plating and processing | |
| | | 0.065mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 2 | Inner Layer 1 | 0.017mm | ED Base Copper | |
| | | 0.100mm | Core IPC-4101/127/128 | FR-4.1 filled, halogen free |
| | | 0.174mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 3 | Inner Layer 2 | 0.017mm | ED Base Copper | |
| | | 0.050mm | Flexible core IPC-4204/11 | Flex Polyimide adhesiveless |
| 4 | Inner Layer 3 | 0.017mm | ED Base Copper | |
| | | 0.060mm | IPC-4101/127/128 + IPC-4203/1 | MIX layer Prepreg + Bondply |
| 5 | Inner Layer 4 | 0.017mm | ED Base Copper | |
| | | 0.050mm | Flexible core IPC-4204/11 | Flex Polyimide adhesiveless |
| 6 | Inner Layer 5 | 0.017mm | ED Base Copper | |
| | | 0.174mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| | | 0.100mm | Core IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 7 | Inner Layer 6 | 0.017mm | ED Base Copper | |
| | | 0.065mm | Prepreg IPC-4101/127/128 | FR-4.1 filled, halogen free |
| 8 | Bottom Side | 0.030mm | Starting foil 1/4oz. after plating and processing | |
| | Bottom Surface Finish | 0.006mm | | |
| | Bottom Solder | 0.015mm | Soldermask IPC-SM840 | used on rigid parts |

Total thickness: 1.041mm

| | | | |
|--|---|--|----------------------|
| notes: | | FLEX8_2Ri-4F-2Ri_104_17_2V13 | |
| Final copper thicknesses according to IPC-6013 | Please follow our sectional design rules: ▶ www.we-online.com/designrigidflex | PCB Thickness Tolerance: rigid ± 10% / flex ± 0,05mm | |
| IPC-2223 use A "Flex to install" | For impedance matching stackups: Please consult our specialists: FLEX@we-online.com | customer | created |
| Standard: Surface Finish ENIG (Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm) | | pcb name | approved |
| | | engineer | format A4, landscape |
| | | date | |
| Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen | | | |



Flex



| # Layer | Thickness | Description | Note |
|---------------------------------|-----------|-------------------------------|------------------------------------|
| Flex Top Coverlay | 0.030mm | PI Coverlay IPC-4203/1 | Polyimide + bonding film (Acrylic) |
| 3 Inner Layer 2 | 0.017mm | ED Base Copper | |
| | 0.050mm | Flexible core IPC-4204/11 | Flex Polyimide adhesiveless |
| 4 Inner Layer 3 | 0.017mm | ED Base Copper | |
| | 0.060mm | IPC-4101/127/128 + IPC-4203/1 | MIX layer Prepreg + Bondply |
| 5 Inner Layer 4 | 0.017mm | ED Base Copper | |
| | 0.050mm | Flexible core IPC-4204/11 | Flex Polyimide adhesiveless |
| 6 Inner Layer 5 | 0.017mm | ED Base Copper | |
| Flex Bottom Coverlay | 0.030mm | PI Coverlay IPC-4203/1 | Polyimide + bonding film (Acrylic) |
| Total thickness: 0.288mm | | | |

| | | | |
|--|---|--|----------------------|
| notes: | | FLEX8_2Ri-4F-2Ri_104_17_2V13 | |
| Final copper thicknesses according to IPC-6013 | Please follow our sectional design rules: ▶ www.we-online.com/designrigidflex | PCB Thickness Tolerance: rigid ± 10% / flex ± 0,05mm | |
| IPC-2223 use A "Flex to install" | For impedance matching stackups: Please consult our specialists: FLEX@we-online.com | customer | created |
| Standard: Surface Finish ENIG (Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm) | | pcb name | approved |
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